constituted by a wire bonding coupling for example an output of the Integrated Circuit die to an output terminal. This is feasible if the length of a wire bonding is ½λ or ¼λ of the to be received or transmitted radio signal wavelength. As an alternative embodiment, a metal lead-frame inside the Integrated Circuit package is used as a radio frequency antenna.

Page 3, please cancel the first, third and fifth full paragraphs.

Page 4, please cancel the first full paragraph.

IN THE CLAIMS:

Please cancel claim 3 without prejudice or disclaimer.

Please enter the following amended claims:

1. (*Twice Amended*) A packaged integrated circuit, comprising at least one radio frequency component included in an integrated circuit die directly connected by wire to a radio frequency antenna, said integrated circuit die being included in said packaged integrated circuit, wherein said radio frequency antenna comprises a portion of the package of said packaged integrated circuit and is excluded from said integrated circuit die.

2. (*Twice Amended*) The packaged integrated circuit according to claim 1, wherein said packaged integrated circuit comprises an integrated circuit package which houses said at least one radio frequency component and wherein said radio frequency antenna comprises at least one metal object that is a portion of the package of said packaged integrated circuit.

4. (*Twice Amended*) The packaged integrated circuit according to claim 2, wherein said radio frequency antenna is disposed on a metal frame of said integrated circuit package.

13. (*Amended*) A module, comprising:

an integrated circuit die having at least one radio frequency component;

a radio frequency antenna;

a shield interposed between said integrated circuit die and said radio frequency antenna, wherein said integrated circuit is directly connected to said radio frequency antenna by metal wiring routed through said shield.

20. (*Amended*) The module according to claim 19, wherein two of said plurality of via holes are disposed opposite each other on said periphery of said antenna.

21. (*Amended*) The module according to claim 13, further comprising an integrated circuit package having a metal frame, said integrated circuit package encapsulating said shield and said integrated circuit die.

22. (*Amended*) The module according to 21, wherein said radio frequency antenna is disposed on said metal frame of said integrated circuit package.

Please add the following new claim:

27. (*New*) The packaged integrated circuit according to claim 1, wherein the length of said wire is ¼λ to ½λ, wherein λ represents the wavelength of a transmitted or received radio signal.